

Features

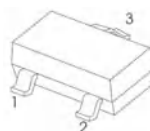
High density cell design for low $R_{DS(ON)}$
Voltage controlled small signal switch
Rugged and reliable
High saturation current capability

V_{DSS} 50 V
 I_D 220 mA
 $R_{DS(ON)}$ 1.7 Ω

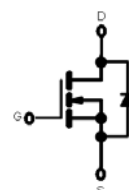
SS

SOT-23

1. GATE
2. SOURCE
3. DRAIN



Equivalent Circuit



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	50	V
Continuous Gate-Source Voltage	V_{GSS}	± 20	
Continuous Drain Current	I_D	0.22	A
Power Dissipation	P_D	0.35	W
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	357	$^{\circ}\text{C/W}$
Operating Temperature	T_j	150	$^{\circ}\text{C}$
Storage Temperature	T_{stg}	-55 ~ +150	

Electrical Characteristics ($T_a=25^{\circ}\text{C}$ unless otherwise noted)

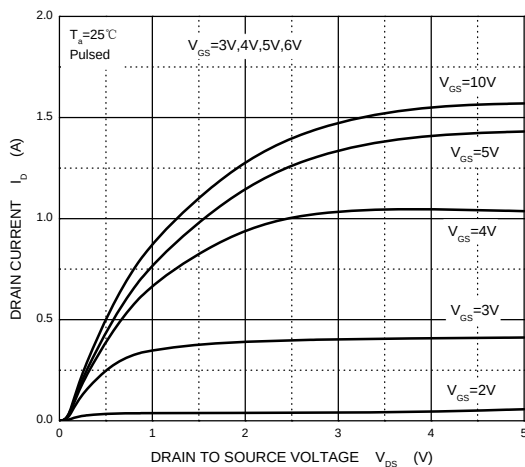
Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D =250μA	50			V
Gate-body leakage	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±10	μA
Zero gate voltage drain current	I _{DSS}	V _{DS} =50V, V _{GS} =0V			0.5	μA
		V _{DS} =30V, V _{GS} =0V			100	nA
On characteristics						
Gate-threshold voltage (note 1)	V _{GS(th)}	V _{DS} =V _{GS} , I _D =1mA	0.80		1.50	V
Static drain-source on-resistance (note 1)	R _{DS(on)}	V _{GS} =10V, I _D =0.22A		1.7	3.50	Ω
		V _{GS} =4.5V, I _D =0.22A			6	
Forward transconductance (note 1)	g _{FS}	V _{DS} =10V, I _D =0.22A	0.12			S
Dynamic characteristics (note 2)						
Input capacitance	C _{iss}	V _{DS} =25V,V _{GS} =0V, f=1MHz		27		pF
Output capacitance	C _{oss}			13		
Reverse transfer capacitance	C _{rss}			6		
Switching characteristics						
Turn-on delay time (note 1,2)	t _{d(on)}	V _{DD} =30V, V _{DS} =10V, I _D =0.29A,R _{GEN} =6Ω			5	ns
Rise time (note 1,2)	t _r				18	
Turn-off delay time (note 1,2)	t _{d(off)}				36	
Fall time (note 1,2)	t _f				14	
Drain-source body diode characteristics						
Body diode forward voltage (note 1)	V _{SD}	I _S =0.44A, V _{GS} = 0V			1.4	V

Notes:

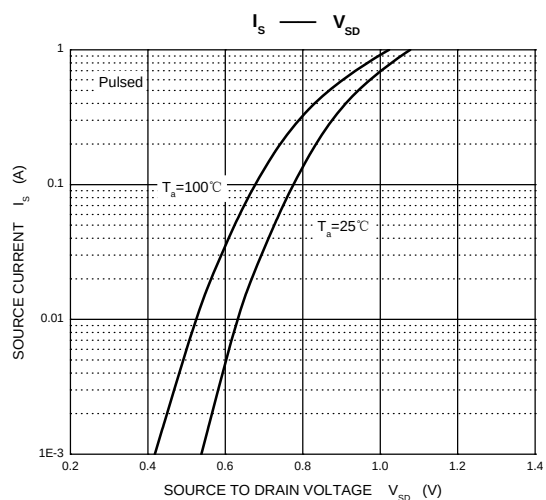
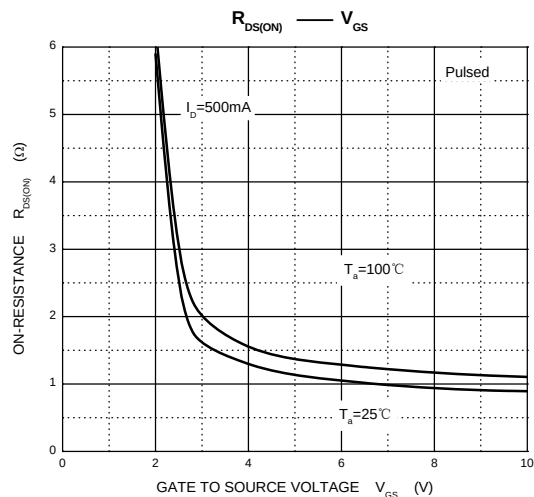
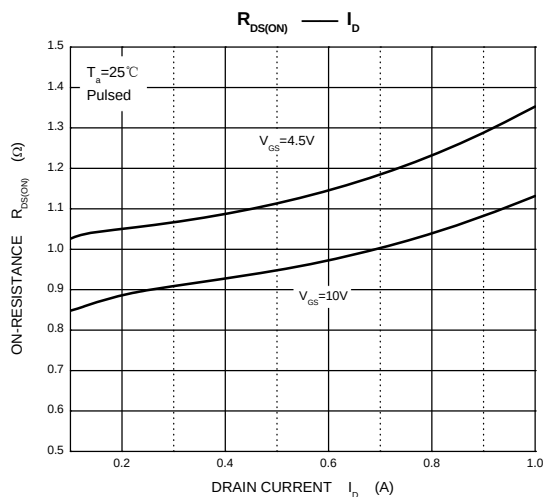
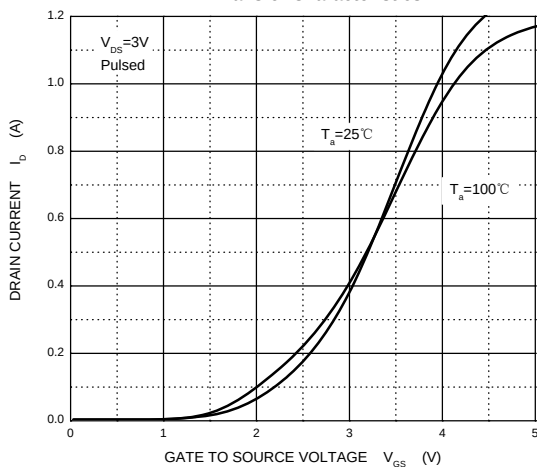
1. Pulse Test ; Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
2. These parameters have no way to verify.

RATING AND CHARACTERISTIC CURVES

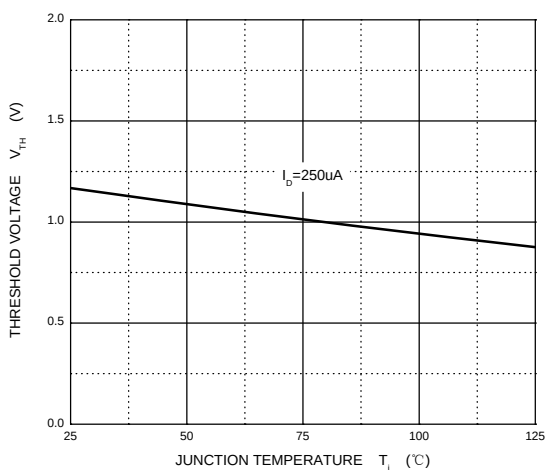
Output Characteristics



Transfer Characteristics

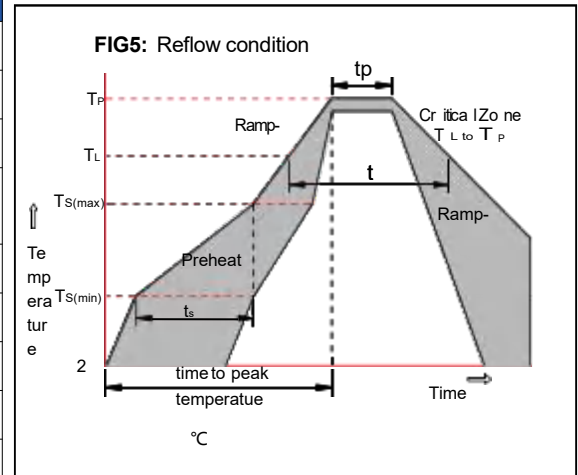


Threshold Voltage



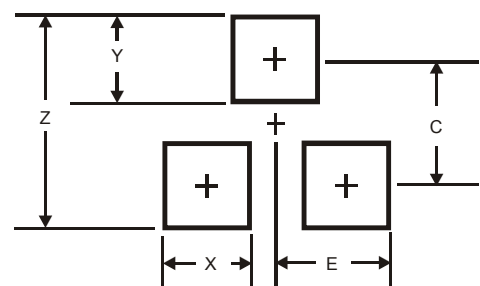
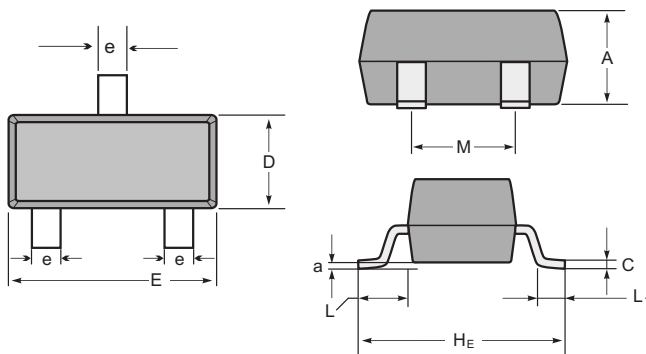
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C



Package Dimensions & Suggested Pad Layout

SOT23



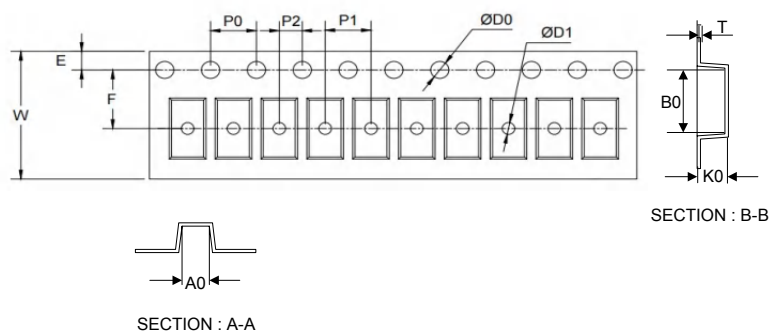
SOT-23 mechanical data

UNIT		A	C	D	E	H _E	e	M	L	L ₁	a
mm	max	1.1	0.15	1.4	3.0	2.6	0.5	1.95	0.55 (ref)	0.36 (ref)	0.0
	min	0.9	0.08	1.2	2.8	2.2	0.3	1.7			0.15
mil	max	43	6	55	118	102	20	77	22 (ref)	14 (ref)	0.0
	min	35	3	47	110	87	12	67			6

Dimensions	SOT23
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

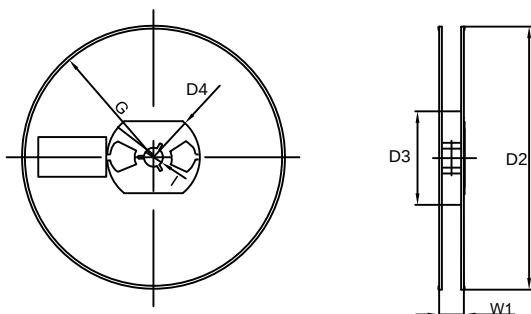
Tape & reel specification

Tape



Symbol	Dimension (mm)
P0	4.00±0.10
P1	4.00±0.10
P2	2.00±0.10
D0	1.55±0.10
D1	1.05±0.10
E	1.55±0.10
F	3.60±0.10
W	8.00±0.10
A0	3.80±0.20
B0	3.25±0.20
K0	1.45±0.10
T	0.25±0.05
D2	178.0±3.0
D3	55Min.
D4	R24.0±3.0
G	R82.0±3.0
I	13.0±2.0
W1	11.0±3.0

7" Reel



Quantity: 3000PCS